What is claimed is:

1. A method for analyzing accuracy of industrial measurement data, the method comprising the steps of:

compiling a plurality of measurements of a primary characteristic from a representative cross-section of a population of devices;

providing a modeling function;

determining a variance from the modeling function for each measurement in the plurality of measurements to form a corresponding plurality of variances;

evaluating the plurality of variances for discontinuities;

identifying a discontinuity within the plurality of variances; and

utilizing the discontinuity to determine a demarcation between accurate and inaccurate measurement data.

2. The method of claim 1, wherein the industrial measurement data comprises semiconductor manufacturing measurement data.

3. The method of claim 1, wherein the step of compiling a plurality of measurements further comprises compiling a plurality of measurements from a profilometer.

4. The method of claim 2, wherein the primary characteristic comprises dishing in metal.

5. The method of claim 2, wherein the primary characteristic comprises dishing in copper.

6. The method of claim 1, wherein the representative cross-section of a population of devices comprises multiple sites around a single device.

7. The method of claim 1, wherein the representative cross-section of a population of devices comprises multiple devices within the population of devices.

8. The method of claim 1, wherein the step of providing a modeling function further comprises providing a constant value.

9. The method of claim 1, wherein the step of providing a modeling function further comprises providing a function relating the primary characteristic to a secondary characteristic.

10. The method of claim 9, wherein the function is linear.

11. The method of claim 9, wherein the function is parabolic.

12. The method of claim 1, wherein the step of determining a variance from the modeling function further comprises determining a residual value.

13. The method of claim 1, wherein the step of evaluating the plurality of variances for discontinuities further comprises a graphical evaluation.

14. The method of claim 13, wherein at least a portion of the graphical evaluation is manual.

15. The method of claim 1, wherein the step of evaluating the plurality of variances for discontinuities further comprises a non-graphical evaluation.

16. The method of claim 15, wherein at least a portion of the non-graphical evaluation is manual.

17. The method of claim 15, wherein the non-graphical evaluation is performed exclusively by a processor.

18. A system analyzing the accuracy of industrial measurement data, the system comprising:

a construct for compiling a plurality of measurements of a primary characteristic from a representative cross-section of a population of devices;

a modeling function;

a construct for determining a variance from the modeling function for each measurement in the plurality of measurements to form a corresponding plurality of variances;

a construct for evaluating the plurality of variances for discontinuities;

a construct for identifying a discontinuity within the plurality of variances; and

a construct for determining a demarcation between accurate and inaccurate measurement data based on the discontinuity.

19. A method for analyzing accuracy of post-CMP dishing measurements rendered by a profilometer in a semiconductor manufacturing process, the method comprising the steps of:

compiling a plurality of dishing measurements from a representative cross-section of semiconductor devices;

providing a modeling function;

determining a variance from the modeling function for each dishing measurement in the plurality of dishing measurements to form a corresponding plurality of variances;

evaluating the plurality of variances for discontinuities;

identifying a discontinuity within the plurality of variances; and

utilizing the discontinuity to determine a demarcation between accurate and inaccurate dishing measurement data.

20. The method of claim 19, wherein the dishing comprises dishing in metal.

21. The method of claim 19, wherein the dishing comprises dishing in copper.

22. The method of claim 19, wherein the representative cross-section of semiconductor devices comprises multiple sites around a semiconductor wafer.

23. The method of claim 19, wherein the representative cross-section of semiconductor devices comprises multiple semiconductor wafers within a lot of semiconductor wafers.

24. The method of claim 19, wherein the representative cross-section of semiconductor devices comprises multiple semiconductor wafers within multiple lots of semiconductor wafers.

25. The method of claim 19, wherein the step of providing a modeling function further comprises providing a constant value.

26. The method of claim 19, wherein the step of providing a modeling function further comprises providing a function relating the dishing to a secondary characteristic.

27. The method of claim 26, wherein the step of providing a modeling function further comprises providing a function relating the dishing to reticle density.

28. The method of claim 26, wherein the function is linear.

29. The method of claim 26, wherein the function is parabolic.

30. The method of claim 19, wherein the step of determining a variance from the modeling function further comprises determining a residual value.

31. The method of claim 19, wherein the step of evaluating the plurality of variances for discontinuities further comprises a graphical evaluation.

32. The method of claim 31, wherein at least a portion of the graphical evaluation is manual.

33. The method of claim 19, wherein the step of evaluating the plurality of variances for discontinuities further comprises a non-graphical evaluation.

34. The method of claim 33, wherein at least a portion of the non-graphical evaluation is manual.

35. The method of claim 33, wherein the non-graphical evaluation is performed exclusively by a processor.